

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.08165**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002855	1000000	34966.2890625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	366601.03125		
		Iron (Fe)	7439-89-6	0.000737	24000	9026.32421875		
		Phosphorus (P)	7723-14-0	0.000009	300	110.226486206		
		Zinc (Zn)	7440-66-6	0.000021	700	257.195129395		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>375994.78125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	27827.0449219		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>27827.0449219</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	3012.85717773		
<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>3012.85717773</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000876	750000	10728.7099609		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000292	250000	3576.23706055		
<b>Die Attach Total:</b>				<b>0.001168</b>	<b>1000000</b>	<b>14304.9482422</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006623	150000	81114.4375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036203	820000	443392.15625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001104	25000	13521.1152344		
		Carbon Black (C)	1333-86-4	0.000221	5000	2706.67260742		
		<b>Encapsulation Total:</b>				<b>0.044151</b>	<b>1000000</b>	<b>540734.4375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000258	1000000	3159.82568359		
					<b>TOTAL MASS (g) :</b>	<b>0.08165</b>		